

MALS062G

Silicon planar type

For ESD protection

■ Overview

MALS062G is optimal for cell phones and AV application, all types of I/O circuits.

■ Features

- High resistance to surge voltages: 30 kV guaranteed
- Low terminal capacitance C_t for low loss, low distortion, and good retention of signal waveforms.

■ Package

- Code
SSMini2-F4
- Pin Name
1: Anode
2: Cathode

■ Marking Symbol: DE

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Total power dissipation *1	P_T	150	mW
Electrostatic discharge *2	ESD	± 30	kV
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *1: $P_T = 150$ mW achieved with a printed circuit board.

*2: Test method: IEC61000-4-2 ($C = 150$ pF, $R = 330 \Omega$, Contact discharge: 10 times)

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Breakdown voltage *	V_{BR}	$I_R = 1$ mA	5.8	6.2	6.6	V
Reverse current	I_R	$V_R = 4$ V			1	μA
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz		55		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

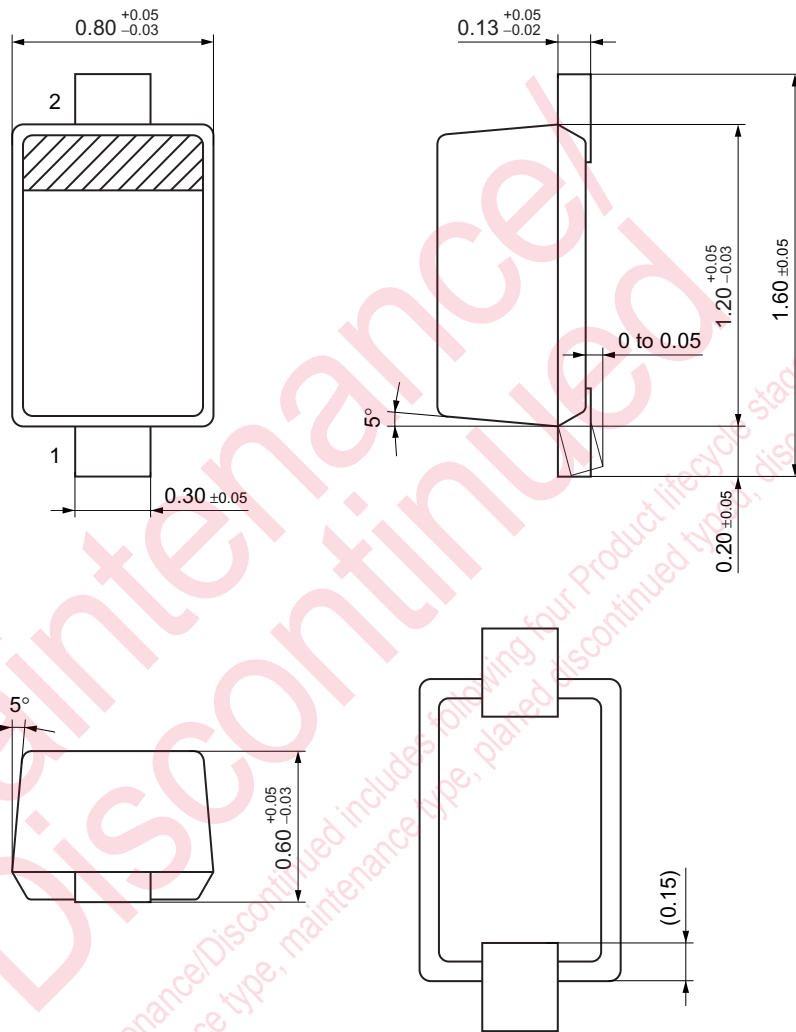
2. *: V_{BR} guaranteed 20 ms after current flow.

The temperature must be controlled 25°C for V_{BR} measurement.

V_{BR} value measured at other temperature must be adjusted to $V_{BR}(25^\circ\text{C})$.

SSMini2-F4

Unit: mm



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